

## ERRATUM TO

# Chapter 7 Chip Size Packaging (CSP) for RF MEMS Devices

Li Xiao and Honglang Li

© Springer International Publishing AG 2017  
K. Kuang, R. Sturdivant (eds.), *RF and Microwave Microelectronics Packaging II*,  
DOI 10.1007/978-3-319-51697-4\_7

---

**DOI 10.1007/978-3-319-51697-4\_12**

The original version of this book was inadvertently published with an incorrect author name in chapter 7. The correct author names are:

Li Xiao and Honglang Li

---

The updated original online version of this chapter can be found at  
[http://dx.doi.org/10.1007/978-3-319-51697-4\\_7](http://dx.doi.org/10.1007/978-3-319-51697-4_7)

---